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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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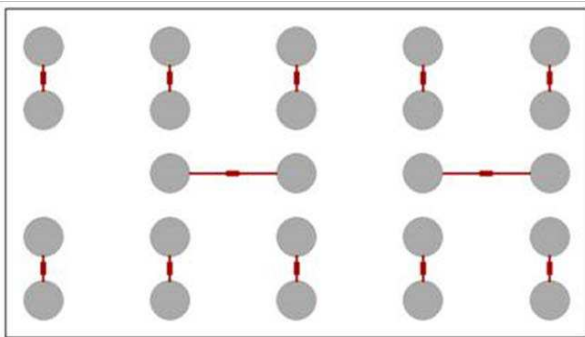
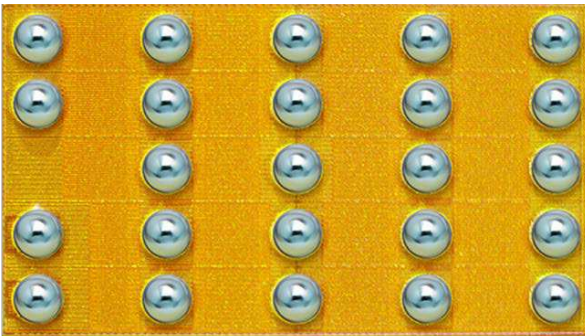
## EPCDESIGNTOOL\_RP-DC Mechanical Die for Daisy Chain Testing

EPCDESIGNTOOL\_RP-DC are sized equivalent to EPC family of devices [EPC2029](#), [EPC2030](#), [EPC2031](#), [EPC2032](#), [EPC2033](#), [EPC2034](#) with die size 4.6 mm x 2.6 mm.

Daisy chain test devices are suitable for a wide variety of process-related testing, such as life cycle testing, drop testing, thermal testing, and optimizing the assembly process.

Daisy-chained packages are wired to provide a continuous path through the package for easy testing as shown in Figure 1 below.

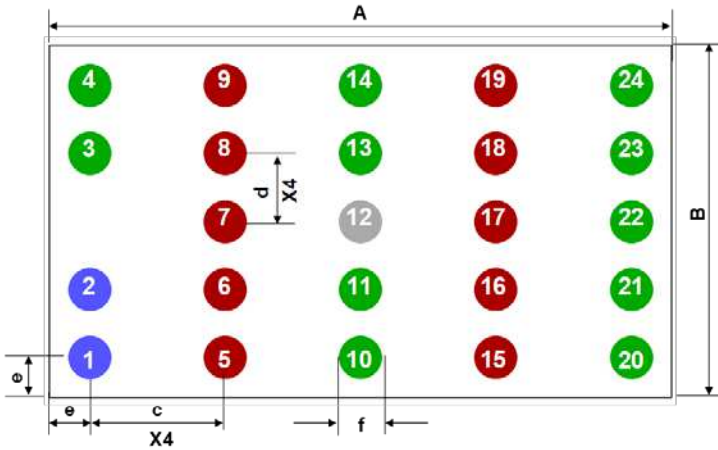
**Figure 1: Daisy Chain Connections for EPCDESIGNTOOL\_RP-DC**



# EPCDESIGNTOOL\_RP-DC

## Mechanical Die for Daisy Chain Testing

Figure 2: Die Outline (Solder Bar View) –



DIM	MICROMETERS		
	MIN	Nominal	MAX
A	4570	4600	4630
B	2570	2600	2630
c	1000	1000	1000
d	500	500	500
e	285	300	315
f	332	369	406

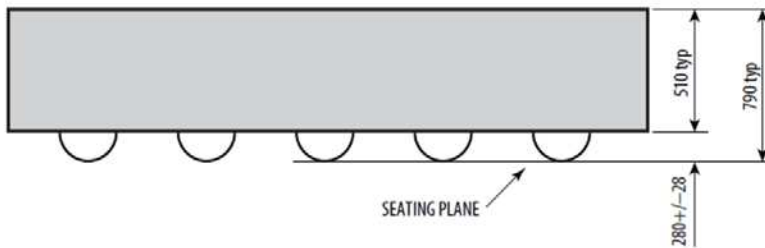
Pads 1 and 2 are Gate;

Pads 5, 6, 7, 8, 15, 16, 17, 18, 19 are Drain;

Pads 3, 4, 10, 11, 13, 14, 20, 21, 22, 23, 24 are Source;

Pad 12 is Substrate

Figure 3: Side View



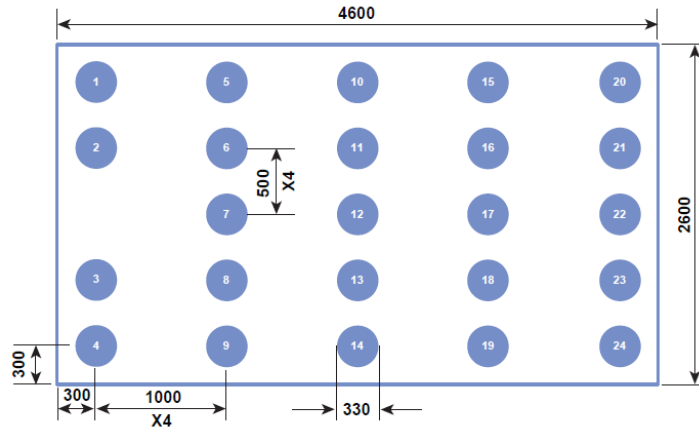


# EPCDESIGNTOOL\_RP-DC

## Mechanical Die for Daisy Chain Testing

**Figure 4: Recommended Land Pattern (units in  $\mu\text{m}$ )**

When a daisy-chained package is assembled on the PCB, a complete circuit is formed, which allows continuity testing. The circuit includes the solder balls, the metal pattern on the die, the bond wires, and the PCB traces.



Land pattern is solder mask defined  
 Solder mask opening is 330  $\mu\text{m}$   
 It is recommended to have on-Cu trace PCB vias

**Pads 1 and 2 are Gate;**

**Pads 5, 6, 7, 8, 9, 15, 16, 17, 18, 19 are Drain;**

**Pads 3, 4, 10, 11, 13, 14, 20, 21, 22, 23, 24 are Source;**

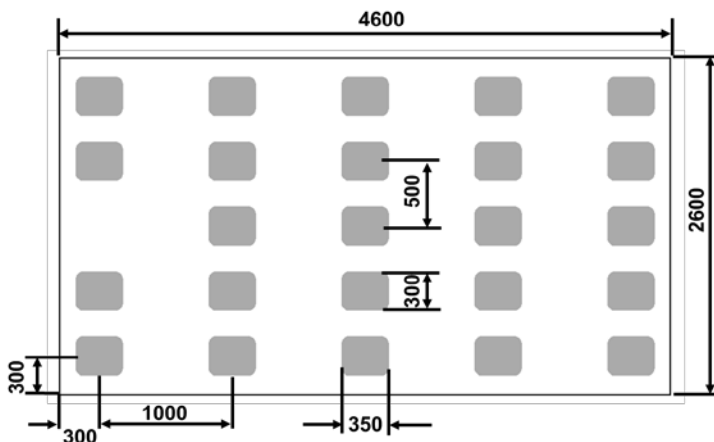
**Pad 12 is Substrate**

**Figure 5: Recommended Stencil Pattern (units in  $\mu\text{m}$ )**

Intended for use with SAC305 Type 3 solder.

Recommended stencil should be 4mil (100  $\mu\text{m}$ ) thick, must be laser cut, openings per drawing.

Additional assembly resources available at [epc-co.com/epc/DesignSupport/AssemblyBasics.aspx](http://epc-co.com/epc/DesignSupport/AssemblyBasics.aspx)



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